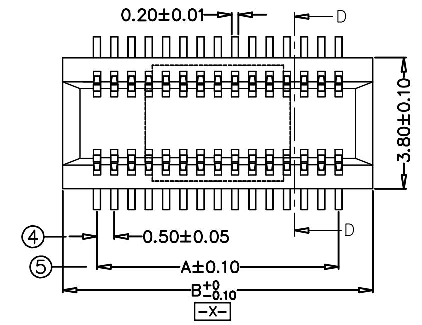
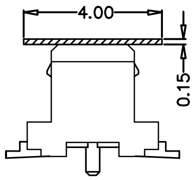
CIRCUITS	DIM A	DIM B	TWN		NHK	
			With Peg	W/Peg	With Peg	W/Peg
10	2.00	3.98	◎	○	⊕	⊕
12	2.50	4.48	◎	○	⊕	
14	3.00	4.98	⊕	○	⊕	
16	3.50	5.48	◎	○	⊕	
18	4.00	5.98	◎	○		
20	4.50	6.48	◎	○	⊕	
22	5.00	6.98	◎	○	⊕	
24	5.50	7.48	◎	○	⊕	
26	6.00	7.98	◎	○	⊕	
28	6.50	8.48	◎	○	⊕	
30	7.00	8.98	◎	○	⊕	
32	7.50	9.48	◎	○	⊕	
34	8.00	9.98	◎	○	⊕	
36	8.50	10.48	◎	○	⊕	
38	9.00	10.98	◎	○		
40	9.50	11.48	◎	○	⊕	
42	10.00	11.98	◎	○		
44	10.50	12.48	◎	○	⊕	
46	11.00	12.98	◎	○	⊕	
48	11.50	13.48	◎	○		
50	12.00	13.98	◎	○	⊕	
52	12.50	14.48	◎	○		
54	13.00	14.98	◎	○		
56	13.50	15.48	◎	○		
58	14.00	15.98	◎	○		
60	14.50	16.48	◎	○	⊕	⊕
62	15.00	16.98	◎	○		
64	15.50	17.48	◎	○		
66	16.00	17.98	◎	○		
68	16.50	18.48	◎	○		
70	17.00	18.98	◎	○		
72	17.50	19.48	◎	○		
74	18.00	19.98	◎	○		
76	18.50	20.48	◎	○		
78	19.00	20.98	◎	○		
80	19.50	21.48	◎	○	⊕	⊕
82	20.00	21.98	◎	○		
84	20.50	22.48	◎	○		
86	21.00	22.98	◎	○		
88	21.50	23.48	◎	○		
90	22.00	23.98	◎	○		
92	22.50	24.48	◎	○		
94	23.00	24.98	◎	○		
96	23.50	25.48	◎	○		
98	24.00	25.98	◎	○		
100	24.50	26.48	◎	○		
110	27.00	28.98	◎	○		
120	29.50	31.48	◎	○		⊕





SPECIFICATIONS

Current Rating:	0.3 Amps AC/DC Max.
Insulator Resistance:	100 Megohms min.
Contact Resistance:	60m ohm Max.
Dielectric withstanding:	AC 500V
Durability:	30 Cycles Min.
Contact Retention:	150g Min. Per contact
Extraction Force:	11g Min Per Contact
Insertion Force:	110g Max Per Contact

MPAS1-XX XX X X-FG

S=Straight

NO. OF CONTACTS

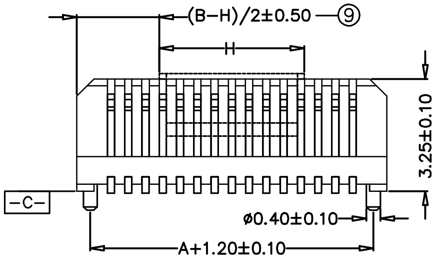
PLATING

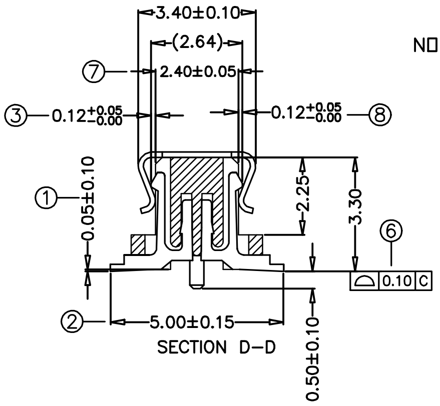
Definition			Code
◎ Tin plated:			VA
◎ Gold plated:			
flash	VB	10μ"	VE
		15μ"	VF
		30μ"	VJ
◎ Duplex Plating:			
flash	VK	10μ"	VP
		15μ"	VN
		30μ"	VU
◎Standard: VB			

0:w/o Locating Peg
1:With Locating Peg

Packacging:
Null: Tube (w/o Film)
K:Reel(w/o Film)
C:Film&Reel
B:MPad&Reel
E:MPad&Tube
F:Film&Tube

FG: RoHS Compliant





SECTION D−D

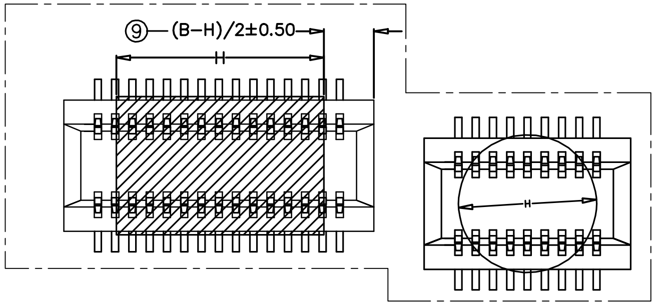


Diagram	Molding description
○	mass production & assemble mold
◎	sample & assemble mold
⊕	mass production & fix mold
⊕	sample & fix mold

PIN	FILM/MPAD P/N	DIM.H
10~18	KT004	ø4.00
20~120	KT021	6.00
10~120	MPAD0014	4.20

FILM	1	KT021/KT004	KAPTON FILM
MPAD	1	MPAD0014	SUS
CONTACT	OP'	B0500285−XX	PHOSPHOR BRONZE, GOLD, TIN OR TIN/LEAD PLATING OVER NICKEL
HOUSING	1	ZVA−XXS1−X	THERMOPLASTIC,UL RATED 94V−0.
PART	Q'TY	P/N	MATFRIAL&FINISH

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GENERAL TOLERANCE UNLESS OTHERWISE SPECIFIED					
XXX.	±	X	.XX	±	0.10
XX.	±	X	.XXX	±	X
X.	±	0.50	X.°	±	1°
.X	±	0.30	.X°	±	X°

APTOS
TECHNOLOGY

REV.	A	DRAWN	09/15/09	MPAS1 Series 0.5mm Board to Board Plug	
DATE	09/15/09	CHECKED			
SCALE	As shown	APPROVED		PRODUCT NO.	MPAS1−XXXXXX−FG
UNIT	mm		SIZE A4	FILE NAME:	MPAS1−XXXXXX−FG.dwg